**IMPACT Conference Call for papers is now open!**

**Submit your abstract before June 15**

IMPACT 2018 Conference, which is organized by IEEE EPS-Taipei, iMAPS-Taiwan, ITRI and TPCA, is the largest gathering of packaging and PCB professionals in Taiwan. This year will be held in conjunction with TPCA SHOW 2018 on Oct. 24th-26th at Taipei Nangang Exhibition Center. For grasping the latest trend, the symposium highlights the theme “***IMPACT on Artificial Intelligence - Our Future***” toward intelligent innovations, which fall into several areas: automobile electionics, smart application, robot, drones, autonomous vehicles, artificial intelligence, Micro LED, 5G and IoT devices. Each application influences a large impact in our daily live. Moreover, plenary speeches, special sessions, invited talks, sponsored industrial sessions, posters and outstanding paper presentations will be arranged.
 IMPACT Conference keeps collaborating with international organizations such as ICEP and JIEP from Japan and iNEMI from U.S.A. The valuable influence toward future trends that will shape the platform of high-tech industry and academic research is going to be built in this grand international conference. What are you waiting for? Submitting your papers and arranging your schedule for IMPACT symposium and TPCA show this October !

【Date】Oct 24 (Wed)-26(Fri), 2018

【Venue】Taipei Nangang Exhibition Center

【Theme】IMPACT on Artificial Intelligence - Our Future

【Exhibition】TPCA Show 2018

【On-line Submission】[www.impact.org.tw](http://www.impact.org.tw)
 **SCOPE OF PAPER SOLICITED**

|  |  |
| --- | --- |
| **Packaging** | **PCB** |
| P1. Advanced Packaging Technologies | B1. Advanced and Green Materials |
| P2. Power Electronics Packaging | B2. Test, Quality, AOI, Inspection and Reliability |
| P3. 3D Integration and SiP | B3. HDI and Embedded Technology |
| P4. Wearable Technologies | B4. Electro Deposition and Electrochemical Processing Technology |
| P5. Interconnections & Nanotechnology | B5. Mechatronics and Automation  |
| P6. Modeling, Simulation & Design | B6. Advanced and Emerging Technology |
| P7. Thermal Management |  |
| P8. Advanced Sensor &Microsystems Technology (MST) |  |
| P9. Advanced Materials, Automatic Process & Assembly |  |
| P10. Emerging Systems Packaging Technologies |  |

\* Papers relevant with the above scopes are encouraged to submit but NOT limited to.

\* Conference authority keeps the right to finalize session arrangement.

**【IMPORTANT DATE】**

|  |  |  |
| --- | --- | --- |
| **Item** | **Date** | **Remark** |
| **Abstract Submission Deadline(Camera-ready Version)** | June 15, 2018 | 400-500 wordsSubmit on-line [www.impact.org.tw](http://www.impact.org.tw) |
| **Abstract Acceptance Notification** | July 15, 2018 | Notice sent via email |
| **Advance Program Online** | August 15, 2018 | Advanced program announcement |
| **Full Paper Submission(Camera-ready Version)** | August 25, 2018 | 4 pages including figures and tables.Submitting on-line through conference website and IEEE copyright forms due |

\* Authors of accepted papers including oral presentation and posters should register before the deadline; please be noted that un-registered (paid) papers will be removed from the symposium program.

\* The secretariat keeps the right to modify the agenda.

**PAPER AWARD**

Outstanding Paper Award will be elected by IMPACT Technical Program Committee from student and industrial papers respectively. The paper awardees will be announced and honored next year.

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